

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SZC0-ZZ-0003

Description : QSFP28 2X3 Ass'y
Press-fit
With Outer Lightpipe
Contact Area : 30μ" min. Gold
Packing With Tray



Spec No.
SZC021003-00

Update Date
2021/3/8

Revision
A

Approved	Checked	Prepared



湧德電子 股份有限公司
UDE Corp.

桃園市(33852) 蘆竹區內溪路 68 巷13號

No.13, Ln. 68, Neixi Rd., Luzhu Dist., Taoyuan City (33852), Taiwan

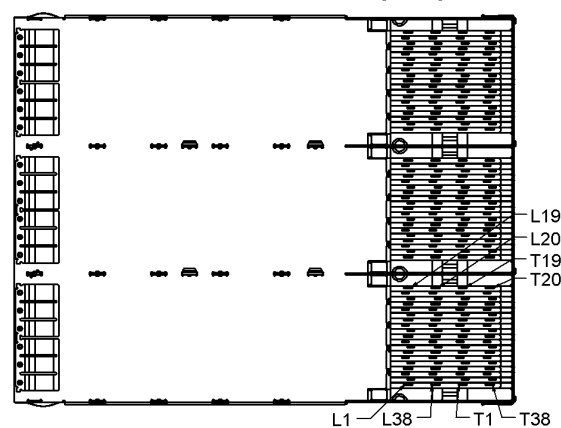
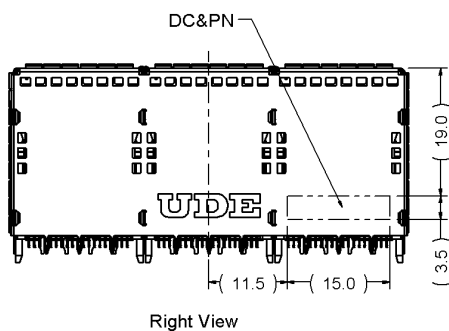
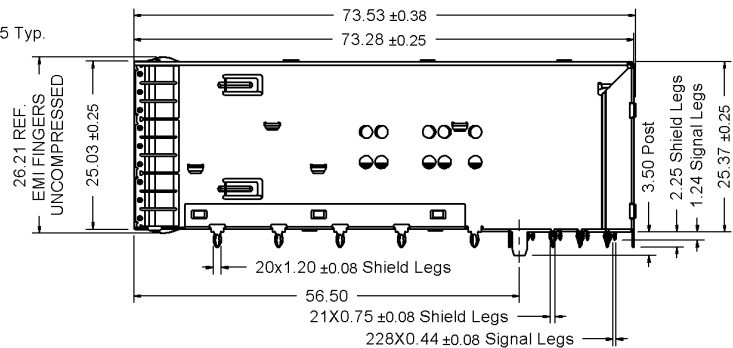
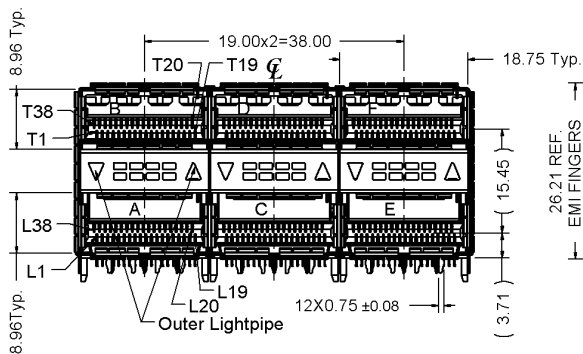
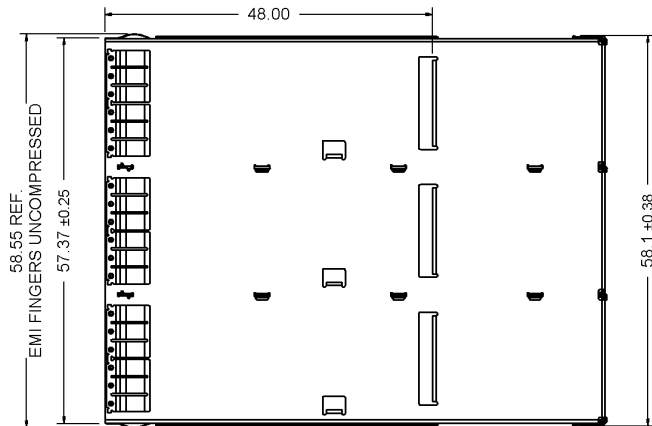
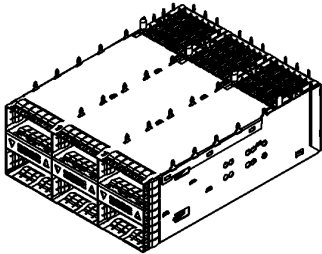
TEL: 886-3-3242000 FAX: 886-3-3246611

<http://www.ude-corp.com/>

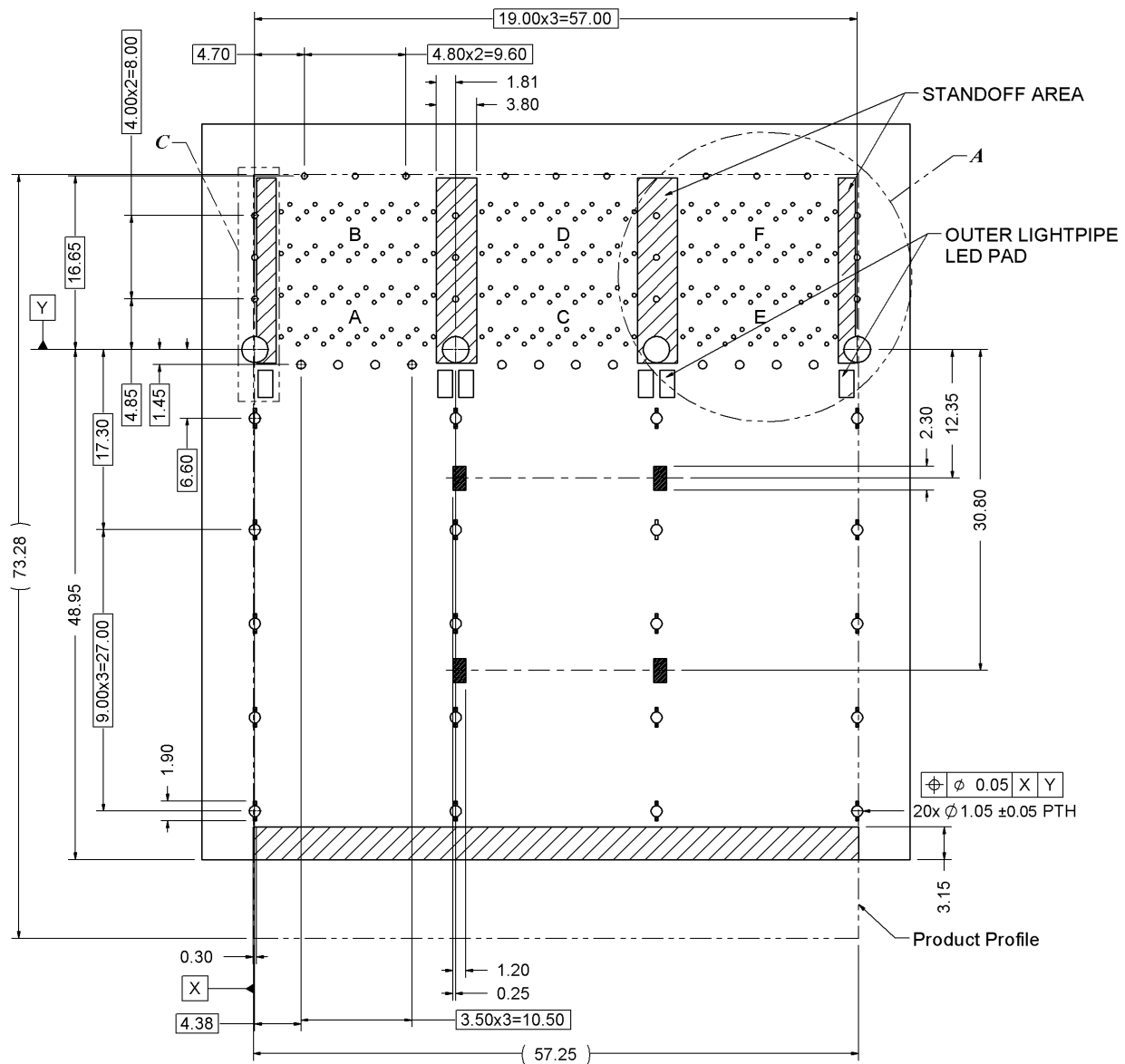
1. MECHANICAL DIMENSION

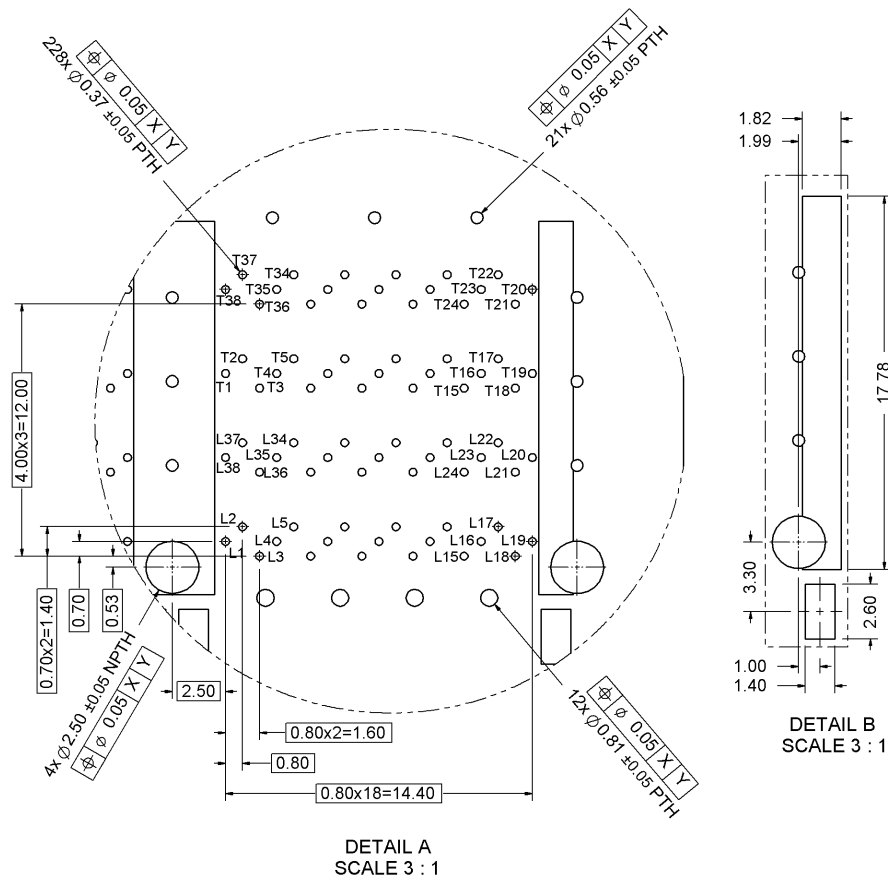
1.1 CAGE assembly Dimension

General Tolerance : X.X : ± 0.38
X.XX : ± 0.20



All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified



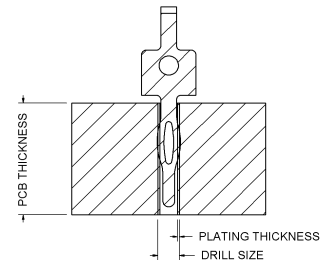


NOTES:

1. THE ENTIRE AREA OF THE CONNECTOR FOOTPRINT, INDICATED BY THE DASHED LINES, TO BE CONSIDERED THE KEEPOUT AREA FOR COMPONENTS
2. CROSS-HATCHED AREAS REPRESENT ZONES ON THE PCB THAT COME IN CONTACT WITH OR BE IN CLOSE PROXIMITY TO THE PLASTIC HOUSING OR THE CAGE. INDICATED AREAS TO BE CONSIDERED TRACE FREE
3. RECOMMENDED THRU HOLE PLATING INCLUDES HASL, OSP, OR IMMERSION (GOLD, SILVER, OR TIN)
4. 1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE
5. HATCHED AREA IS PLACEMENT ZONE FOR LED, LED SHOULD BE CENTERED WITHIN ZONE, RECOMMEND 0805 PACKAGE

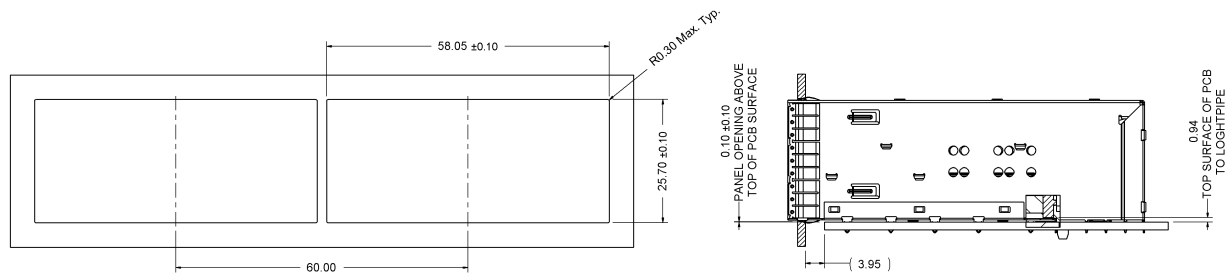
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	1.05 SHIELD PINS	0.81 SHIELD PINS	0.56 SHIELD PINS	0.37 SIGNAL PINS
FINISHED HOLE DIAMETER	1.05 ±0.05	0.81 ±0.05	0.56 ±0.05	0.37 ±0.05
DRILLED HOLE DIAMETER	1.15	0.91	0.66	0.47
COPPER PLATING	0.025 min.	0.025 min.	0.025 min.	0.025 min.



RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

1.3 Recommended Panel Cutout



PRESS-FIT ASSEMBLIES

HAND PLACE USING PROPER SEATING FORCE TO ENGAGE ALL LEG TAILS INTO PLATED THROUGH HOLES

ASSEMBLIES ARE TO BE SEATED PER THE INSTRUCTIONS ASSOCIATED WITH THE APPROPRIATE INSERTION TOOL

NOTE:UDE RECOMMENDS ONLY ONE CONNECTOR ASSEMBLY BE INSTALLED AT A TIME

ASSEMBLY INSERTION FORCE

PORT SIZE	PCB FINISH	FORCE
2X3	Copper w/OSP	1700±170N

1.4 Packing Information

8 pcs finished goods per tray

5trays(40pcs finished goods) per master carton

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

2.2.1 Shield Parts

2.2.1.1 Top Shell : Copper Alloy, Thickness=0.25mm

2.2.1.2 Bottom Shell : Copper Alloy, Thickness=0.25mm

2.2.1.3 EMI Spring Finger : Ph.Bronze, Thickness=0.06mm

Finish : 30μ" min. Nickel

2.2.1.4 RL Mid Ground: Copper Alloy, Thickness=0.25mm

2.2.1.5 UD Mid Ground: Copper Alloy, Thickness=0.25mm

2.2.1.6 Housing: LCP/BK,UL94V-0

2.2.1.7 Terminal IM Plastic: LCP/BK,UL94V-0

2.2.1.8 Terminal: Copper Alloy, Thickness=0.20mm

Finish :

Contact area 30μ"min. Gold Plating, 50μ"min. Nickel overall.

Solder Tail 30μ"min. Matte Tin, 50μ"min. Nickel overall.

2.2.1.9 Outer Lightpipe : PC,UL94V-0,Transparent

2.2.2.0 Lightpipe Cover : PBT/BK,UL94V-0

2.3 Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : -55°C to +105°C

2.4 QSFP28 specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 1000M Ω min.

Dielectric Withstanding Voltage : 300VDC @ 1min.

Insertion force : 60 N MAX.

Extraction force : 30 N MAX.

Cage Retention (Latch strength) : 125N Min.

Durability : 100 cycles for standard class

2.5 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.6 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

